

### **DATASHEET**

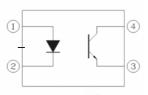
## 4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER **EL816 Series**







#### Schematic



#### Features:

- Compliance Halogens Free (Only copper leadframe) (Br < 900 ppm, Cl < 900 ppm, Br+Cl < 1500 ppm)
- Current transfer ratio (CTR:  $50\sim600\%$  at  $I_F = 5mA$ ,  $V_{CE} = 5V$ ) (CTR:  $63\sim320\%$  at  $I_F = 10mA$ ,  $V_{CE} = 5V$ )
- High isolation voltage between input and output (Viso=5000Vrms)
- Creepage distance > 7.62mm
- Operating temperature up to +110°C
- Compact small outline package
- Pb free
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

### NEMKO approved

**Description** 

The EL816 Series of devices each consist of an infrared emitting diodes, optically coupled to a phototransistor detector.

They are packaged in a 4-pin DIP package and available in wide-lead spacing and SMD option.

### **Applications**

- Programmable controllers
- · System appliances, measuring instruments
- Telecommunication equipments
- Home appliances, such as fan heaters, etc.
- Signal transmission between circuits of different potentials and impedances

#### Pin Configuration

- 1. Anode
- 2. Cathode
- 3. Emitter
- 4. Collector



### **Absolute Maximum Ratings (Ta=25°C)**

	Parameter	Symbol	Rating	Unit
	Forward current	I <sub>F</sub>	60	mA
	Peak forward current (1us, pulse)	I <sub>FP</sub>	1	А
Input	Reverse voltage	$V_{R}$	6	V
	Power Dissipation  No derating required up to $T_a = 100^{\circ}C$	$P_{D}$	100	mW
	Power dissipation	_	150	mW
	Derating factor (above T <sub>a</sub> = 80°C)	P <sub>C</sub> —	5.8	mW/°C
Output	Collector current	Ic	50	mA
	Collector-Emitter voltage	V <sub>CEO</sub>	80	V
	Emitter-Collector voltage	V <sub>ECO</sub>	6	V
Total Powe	er Dissipation	P <sub>TOT</sub>	200	mW
Isolation Voltage*1		V <sub>ISO</sub>	5000	Vrms
Operating Temperature		T <sub>OPR</sub>	-55 to 110	°C
Storage Temperature		T <sub>STG</sub>	-55 to 125	°C
Soldering	Temperature* <sup>2</sup>	T <sub>SOL</sub>	260	°C

#### Notes:

<sup>\*1</sup> AC for 1 minute, R.H.=  $40 \sim 60\%$  R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

<sup>\*2</sup> For 10 seconds



### Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	VF	-	1.2	1.4	V	I <sub>F</sub> = 20mA
Reverse Current	$I_R$	-	-	10	μΑ	V <sub>R</sub> = 4V
Input capacitance	C <sub>in</sub>	-	30	250	pF	V = 0, f = 1kHz

Note: Reverse Voltage(VR) Condition is applied to IR test only The device is not designed for reverse operation Output

Parameter	Symbol	Min	Тур.	Max.	Unit	Condition	
Collector-Emitter dark	I <sub>CEO</sub>	_	_	100	nA	V <sub>CE</sub> = 20V, I <sub>F</sub> = 0mA	
current	ICEO			100	ПА	V CE - 20 V, IF - OIIIA	
Collector-Emitter	$BV_CEO$	80	_	_	V	$I_C = 0.1 \text{mA}$	
breakdown voltage	PACEO	00	_	_	V	IC = 0. IIIIA	
Emitter-Collector	$BV_{ECO}$	6	_	_	V	$I_{E} = 0.1 \text{mA}$	
breakdown voltage	DVECO	U	-	-	v	IE = O. IIIIA	

**Transfer Characteristics** 

Parameter		Symbol	Min	Тур.	Max.	Unit	Condition
	EL816		50	-	600		
	EL816A		80	-	160		
	EL816B	_	130	-	260		
	EL816C	CTR - -	200	-	400	%	$I_F = 5mA$ , $V_{CE} = 5V$
	EL816D		300	-	600		
	EL816X		100	-	200		
Current Transfer ratio	EL816Y		150	-	300		
Transier ratio	EL816I		63	-	125		
	EL816J	_	100	-	200		$I_F = 10 \text{mA}$ , $V_{CE} = 5 \text{V}$
	EL816K	- CTR	160	-	320	0/	
	EL816I	_	22	-	-	%	
	EL816J	_	34	-	-		$I_F = 1mA$ , $V_{CE} = 5V$
	EL816K		56	-	-		



### Transfer Characteristics (T<sub>a</sub>=25°C unless specified otherwise) Continuity

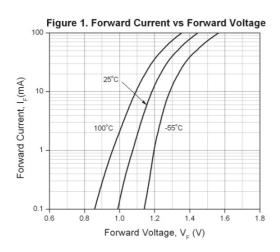
Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
Collector-Emitter saturation voltage	$V_{\text{CE(sat)}}$	-	0.1	0.2	V	$I_F = 20 \text{mA}$ , $I_C = 1 \text{mA}$
Isolation resistance	R <sub>IO</sub>	5×10 <sup>10</sup>	-	-	Ω	$V_{IO} = 500 Vdc,$ 40~60% R.H.
Floating capacitance	$C_{IO}$	-	0.6	1.0	pF	$V_{IO} = 0$ , $f = 1MHz$
Cut-off frequency	fc	-	80	-	kHz	$V_{CE} = 5V$ , $I_C = 2mA$ $R_L = 100\Omega$ , $-3dB$
Rise time	t <sub>r</sub>	-	-	18	μs	$V_{CE} = 2V$ , $I_C = 2mA$ ,
Fall time	t <sub>f</sub>	-	-	18	μs	$R_L = 100\Omega$

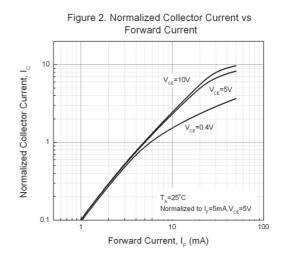
<sup>\*</sup> Typical values at T<sub>a</sub> = 25°C

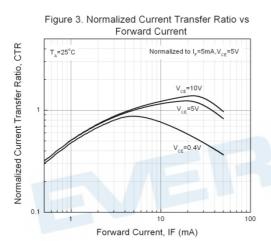


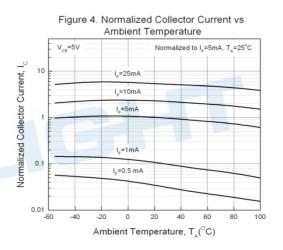


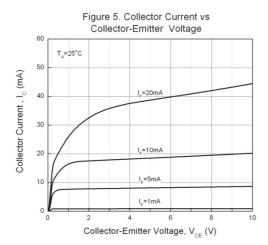
### **Typical Electro-Optical Characteristics Curves**

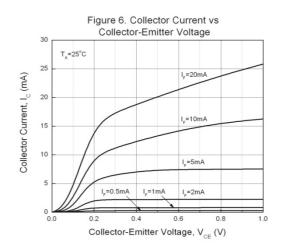




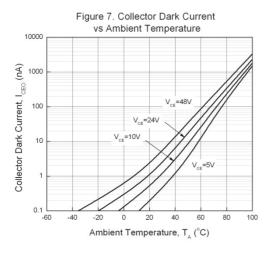


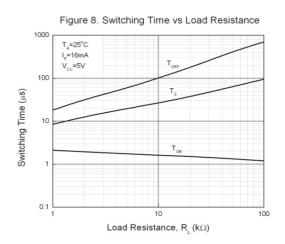


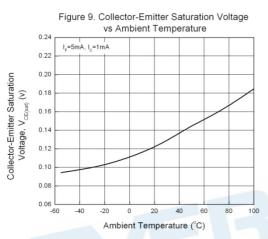


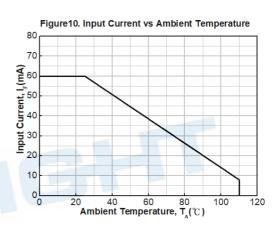












Note: The graphs shown in this datasheet are representing typical data only and do not show guaranteed values

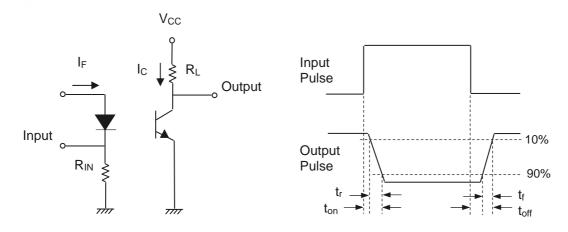


Figure 11. Switching Time Test Circuit & Waveforms



### **Order Information**

#### **Part Number**

# **EL816X(Y)(Z)-FV**

#### Note

X = Lead form option (S1, S2, M or none)

Y = CTR Rank (A, B, C, D, X, Y, I, J, K or none)

Z = Tape and reel option (TU, TD or none).

F = Lead frame option (F: Iron, None: copper)

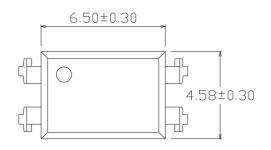
V = VDE safety (optional).

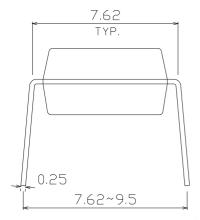
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
М	Wide lead bend (0.4 inch spacing)	100 units per tube
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	2000 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	2000 units per reel
S2 (TU)	Surface mount lead form (low profile) + TU tape & reel option	2000 units per reel
S2 (TD)	Surface mount lead form (low profile) + TD tape & reel option	2000 units per reel

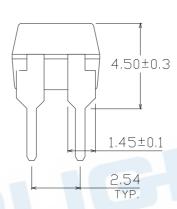


### Package Dimension (Dimensions in mm)

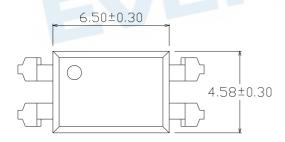
### **Standard DIP Type**

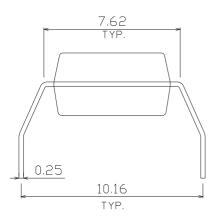


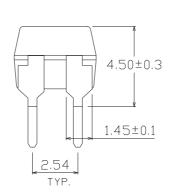




### **Option M Type**

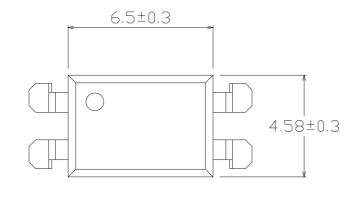


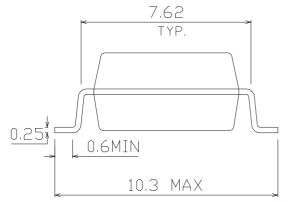


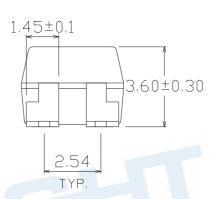




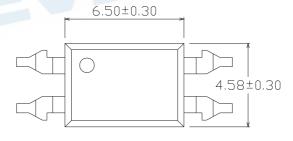
### **Option S1 Type**

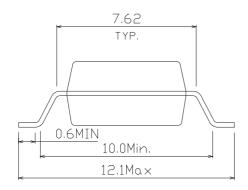


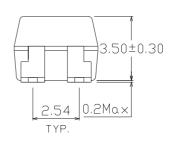




### **Option S2 Type**

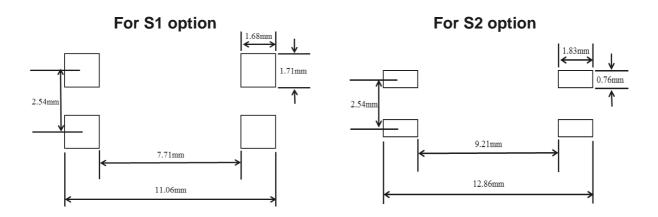








#### Recommended pad layout for surface mount leadform



### **Device Marking**

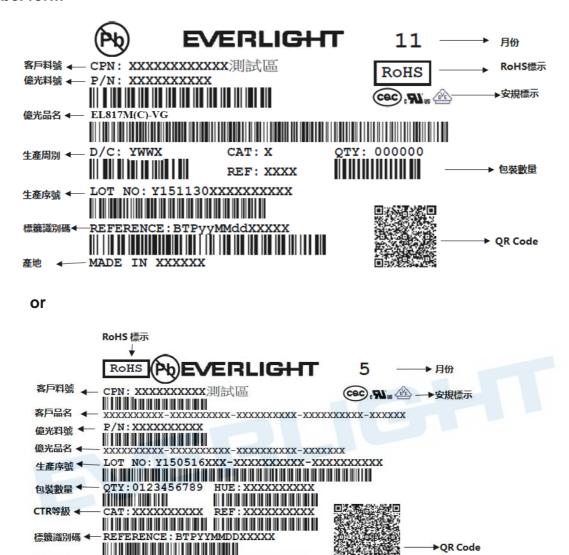


#### **Notes**

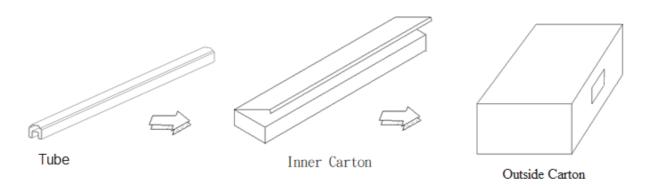
EL	denotes EVERLIGHT
816	denotes Device Number
R	denotes CTR Rank(A, B, C, D, X, Y, I, J, K or none)
Υ	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)



#### Label form



#### **TUBE Dimension**

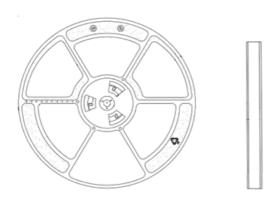


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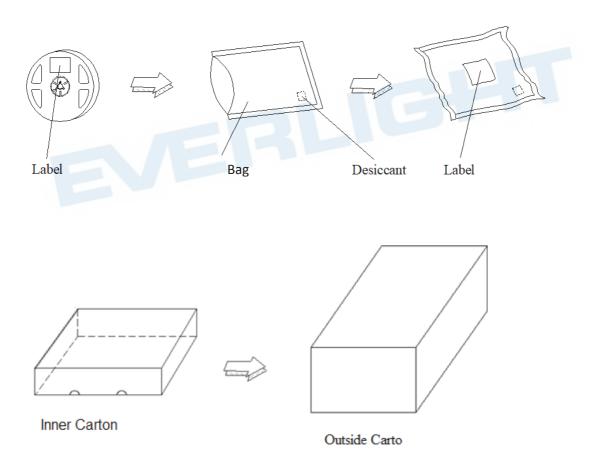
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### **Reel Dimension**

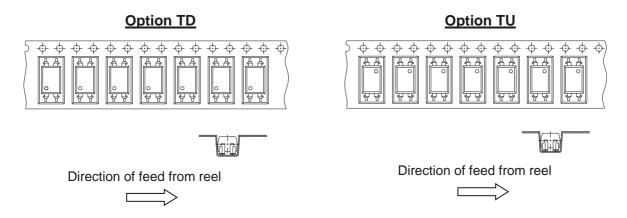


### **Moisture Resistant Packaging**

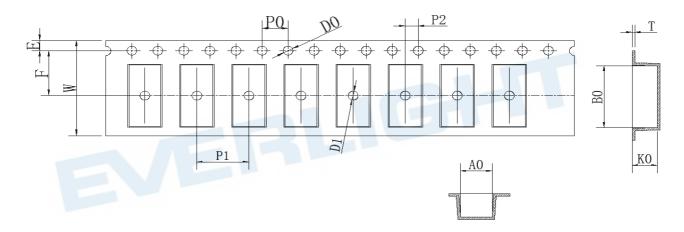




**Tape & Reel Packing Specifications** 



#### **Tape dimensions**



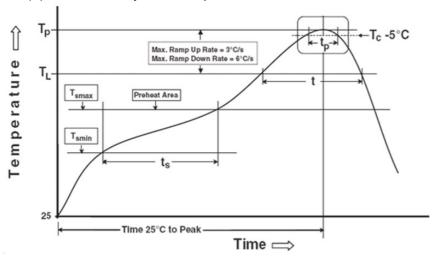
Dimension No.	Ao	Во	Do	D1	E	F
Dimension (mm) S1	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension (mm) S2	4.88±0.1	12.55±0.1	1.5±0.1	1.50±0.1	1.75±0.1	11.5±0.1
Dimension No.	Ро	P1	P2	t	W	Ко
Dimension (mm) S1	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	16.00±0.3	4.00±0.1
Dimension (mm) S2	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	24.00±0.3	4.00±0.1



#### **Precautions for Use**

#### 1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

**Preheat** 

Temperature min (T<sub>smin</sub>)

Temperature max (T<sub>smax</sub>)

Time ( $T_{smin}$  to  $T_{smax}$ ) ( $t_s$ )

Average ramp-up rate (T<sub>smax</sub> to T<sub>p</sub>)

Other

Liquidus Temperature (T<sub>L</sub>)

Time above Liquidus Temperature (t L)

Peak Temperature (T<sub>P</sub>)

Time within 5 °C of Actual Peak Temperature: TP - 5°C

Ramp- Down Rate from Peak Temperature

Time 25°C to peak temperature

Reflow times

Reference: IPC/JEDEC J-STD-020D

150 °C

200°C

60-120 seconds

3 °C/second max

217 °C

60-100 sec

260°C

30 s

6°C /second max.

8 minutes max.

3 times



### **Precautions for General Storage**

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5°C to 35°C and 20 % to 60 %,respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.





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